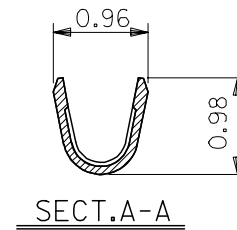
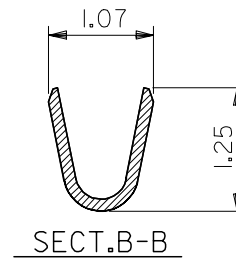
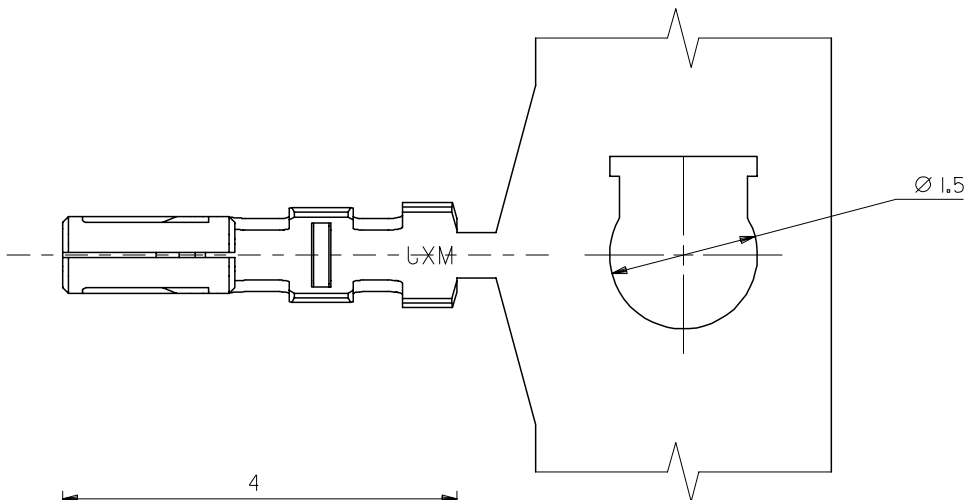
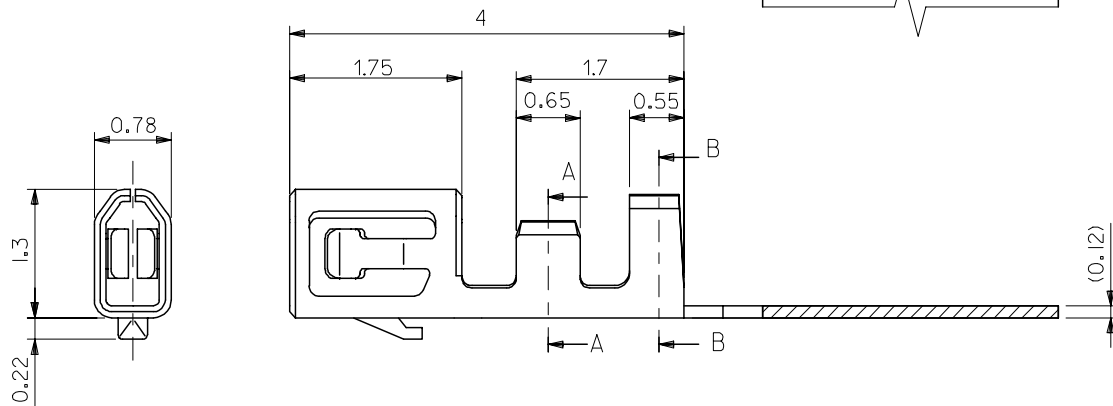


10 9 8 7 6 5 4 3 2 1



NOTES.

- 適合ハウジング: 501189-****
APPLICABLE HOUSING : 501189-****
- メッキ仕様
PLATING
金メッキ: 0.1 μmMIN.
Au PLATING
ニッケルメッキ (下地): 1.0 μmMIN.
Ni PLATING (UNDER PLATING)



501193-0100	バラ状 LOOSE
501193-0000	連続状 CHAIN
MATERIAL NO.	端子形状 FORM

MATERIAL リン青銅 PHOSPHOR BRONZE ±0.12 FINISH SEE NOTE WIRE RANGE AWG#28-32 INS. RANGE φ 0.4-0.8	REVISED EC No: J2005-0329 DRWN: NYOSHIDA 2004/11/02 CHKD: MYAGI 2004/11/02 APPR: ANODA 2004/11/12 DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2004/04/03	TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL		
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2004/04/03			
		30 OVER	±0.3	APPROVED BY MIYAZAWA	DATE 2004/04/03	MOLEX INCORPORATED		
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-501193-001	SHEET NO. 1 OF 1		

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION